

# Oxygen distribution in silicon nitride powders

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The oxygen content of ten different silicon nitride powders was determined by bulk chemical analysis and surface-sensitive X-ray photoemission spectroscopy (XPS). In silicon nitride powders prepared from silicon and silica by nitridation and carbothermal reduction in a nitrogen atmosphere, respectively, only a minor part of the total oxygen content of 0.9 to 2.5 wt% was found in a surface layer of less than 1 nm thick, whereas an appreciable amount can be attributed to oxygen dissolved in the bulk. Powders made by silicon diimide decomposition, however, are characterized by a higher oxygen concentration at the particle surface relative to the bulk, which may be further reduced by chemical treatment. The surface layer composition corresponds to an intermediate state between silica and silicon oxynitride.

## 1. Introduction

Silicon nitride powders of high purity, small and homogeneous grain size are being developed for pressureless sintering of high-temperature resistant silicon nitride ceramics. These powders are mainly produced by nitridation of fine silicon powder, carbothermal reduction of silica and subsequent nitridation, gas-phase reaction of silanes with ammonia and thermal decomposition of silicon diimide [1-3]. Because of the higher free energy of formation of silica, silicon nitride will always be oxidized to silica or silicon oxynitride in the presence of an oxygen or water-containing atmosphere even though the reaction kinetics will be extremely slow at room temperature [4]. Thus the particle surfaces of silicon nitride powders are expected to be covered with an oxide-rich layer, which dominates the interparticle interactions and hence the powder properties such as agglomeration or dispersion in colloidal systems.

Various techniques have been used to characterize the structure and composition of the powder particle surfaces such as TEM, XPS and SIMS [5]. From the results a typical thickness of the oxide layer on several commercial silicon nitride powders of  $\sim 3$  to 5 nm was deduced, with a composition corresponding to silicon oxynitride rather than to silica. From controlled oxidation experiments of clean silicon nitride films, the results of XPS also showed the oxidized layer having the composition of a "graded" oxynitride layer, with the elemental concentration of oxygen decreasing steadily with distance from the surface [6].

In contrast to the oxygen on the particle surface, only little information has yet been reported concerning the oxygen solubility in the bulk of silicon nitride powders. Previously,  $\alpha$ - $\text{Si}_3\text{N}_4$  was considered to be an oxygen-stabilized silicon nitride modification with a composition of  $\text{Si}_{23}\text{N}_{30}\text{O}$  [7, 8]. Subsequent investigations, however, proved the  $\alpha$ -modification to be

stable also in the total absence of oxygen [9]. Nevertheless,  $\alpha$ - $\text{Si}_3\text{N}_4$ , which is the predominant phase modification in commercial silicon nitride powders, is supposed to dissolve a certain amount of oxygen whereas no significant oxygen solubility in  $\beta$ - $\text{Si}_3\text{N}_4$  has yet been reported. While the dissolution of oxygen in pure silicon nitride is associated with the lattice defect structure, it is significantly enhanced by solid solution formation in the presence of certain metal atoms such as aluminium, magnesium, calcium, yttrium, etc. [10].

This study deals with the analysis of the distribution of oxygen in various commercial silicon nitride powders, which were produced by different methods. Surface-sensitive X-ray photoemission spectroscopy (XPS) and chemical analysis of the total oxygen content are applied to characterize the oxygen distribution in these powders.

## 2. Experimental procedure

### 2.1. Powders

Ten commercial silicon nitride powders were examined for their oxygen content: Anzon grade 1001, Warwick, GB (denoted A), Denka 9-FW, Tokyo, Japan (B), Kema Nord P-95, Ljungaverk, Sweden (C), H. C. Starck H-1, Berlin, FRG (D), H. C. Starck LC-10, Berlin, FRG (E), H. C. Starck LC-12, Berlin, FRG (F), Sumitomo Chem. TC-2, Osaka, Japan (G), Toshiba Grade A, Tokyo, Japan (H), Toyo Soda TS-7, Tokyo, Japan (I) and UBE E-10, Tokyo, Japan (K). Six of them, powders A to F, were produced by nitridation of metallic silicon, two by carbothermal reduction of silica in a nitrogen atmosphere, powders G and H, and two by thermal decomposition of silicon diimide, powders I and K.

### 2.2. Preparation of $\text{Si}_2\text{N}_2\text{O}$

Crystalline  $\text{Si}_2\text{N}_2\text{O}$  was prepared as a reference material by hot pressing a eutectic composition of  $\alpha$ - $\text{Si}_3\text{N}_4$

TABLE I XPS electron binding energies (eV)

	Si 2p	O 1s	N 1s
Si <sub>3</sub> N <sub>4</sub> powders	101.1 ± 0.2	532.8 ± 0.2	397.5 ± 0.2
Si <sub>2</sub> N <sub>2</sub> O*	102.1	532.4	298.2
SiO <sub>2</sub> †			
(cristobalite)	103.1 to	532.3 to	
(silica gel)	103.4	532.7	

\*Hot-pressed specimen from [11].

†According to [13].

and SiO<sub>2</sub> with 3 mol % Al<sub>2</sub>O<sub>3</sub> at 1750°C with 35 MPa for 45 min [11]. XRD proved complete reaction to Si<sub>2</sub>N<sub>2</sub>O.

### 2.3. Bulk analysis

The total oxygen content of the powders was analysed by the inert gas fusion technique [12]. 20 to 30 mg dried powder was decomposed in liquid platinum at 2400°C in a graphite die in high vacuum. The oxygen was detected as CO by the change of the heat conductivity. The standard deviation of the mean value was approximately 5%.

### 2.4. Surface analysis

The specific surface area of the powders was measured by the BET method. Equivalent grain sizes assuming spherical grain morphology were deduced from these data and were used for calculation of an equivalent thickness of the surface oxide layers.

X-ray photoelectron spectra (XPS) were obtained with a Leybold-Heraeus LHS-10 system with a hemispherical energy analyser. A base pressure of 10<sup>-6</sup> Pa was maintained during the analyses. Spectra were measured with a MgK $\alpha$  X-ray source (1253.6 eV) and at a constant pass energy of 50 eV. Binding energies were referenced to the C1s peak at 284.6 eV which derives from the ubiquitous carbon contamination and the Scotch tape on to which the powder samples were fixed. For quantitative evaluation of the integrated peak areas (over a tangential baseline) atomic sensitivity factors of 0.63 for the O 1s and 0.38 for the N 1s level were used. These factors have previously been found to correspond well with the transmission function of our spectrometer [13, 14].

## 3. Results and discussion

### 3.1. X-ray photoelectron spectra

X-ray photoelectron spectra were taken from all the Si<sub>3</sub>N<sub>4</sub> powder samples A to K. The O 1s, N 1s and Si 2p signals were, in all cases, rather narrow and at almost identical binding energy levels for the different powders (Table I). The O 1s and N 1s peaks gave no evidence for more than one oxygen or nitrogen species. This is in contrast to previous measurements [5] where at least two different oxygen peaks were found. That at lower binding energy (529.7 eV) was attributed to oxidic oxygen bound to metallic impurities on the surface, e.g. iron oxide. Such a species was not observed in our study. The Si 2p signals were measured at 101.1 eV binding energy and those powders with a higher oxygen content or a thicker oxide layer also showed a weak shoulder at the high  $E_B$  side of the main peak (Fig. 1). In Table I the Si 2p, O 1s, and N 1s

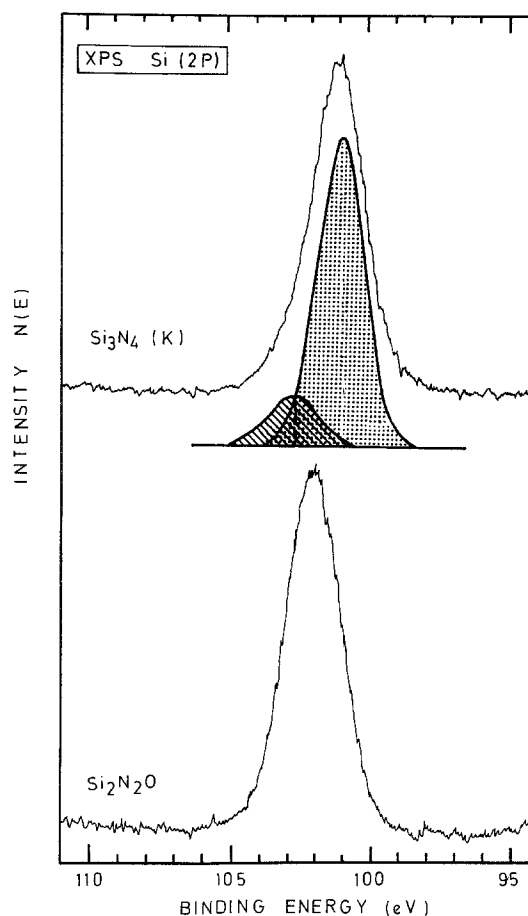


Figure 1 X-ray photoelectron spectra of the Si 2p level for Si<sub>3</sub>N<sub>4</sub> powder (K) and a hot-pressed Si<sub>2</sub>N<sub>2</sub>O sample [11]. The powder spectrum is deconvoluted into two peaks of equal half-width with an intensity ratio of 6.2 to 1 and electron binding energies of 101.1 and 102.8 eV, respectively.

values are compared with literature data of various types of SiO<sub>2</sub> [15] and data obtained from a bulk Si<sub>2</sub>N<sub>2</sub>O sample [11]. The binding energies of the N 1s and the main Si 2p level can be regarded as typical of bulk Si<sub>3</sub>N<sub>4</sub> and Si<sub>2</sub>N<sub>2</sub>O and they reflect the different modes of charge distribution in the compounds [5, 16, 17]. The O 1s level at 532.8 eV of the superficial oxidation layer on Si<sub>3</sub>N<sub>4</sub> is slightly higher than that of Si<sub>2</sub>N<sub>2</sub>O and close to amorphous silica gel or vycor glass [15]. Deconvolution of the Si 2p spectrum of Si<sub>3</sub>N<sub>4</sub> powder K (Fig. 1) revealed a small peak of about 102.8 eV binding energy which lies in between Si<sub>2</sub>N<sub>2</sub>O and SiO<sub>2</sub>. Therefore, a clear identification of the surface layer as SiO<sub>2</sub> or Si<sub>2</sub>N<sub>2</sub>O cannot be made. An interpretation of our data in terms of a non-stoichiometric and, perhaps, amorphous oxynitride with a higher oxygen content than in crystalline Si<sub>2</sub>N<sub>2</sub>O seems more likely [16]. Also, a continuously changing or even layered structure could be in accord with our spectra [5].

### 3.2. XPS-derived oxide-layer thickness, $d_{XPS}$

From the relative O 1s and N 1s peak intensities it should be possible to calculate an equivalent thickness of the surface oxide layer assuming an ordered structure of a SiO<sub>2</sub> layer on the surface of the Si<sub>3</sub>N<sub>4</sub> grains. The results obtained with such an idealized model do not vary significantly from results one would obtain with a

more complex layer structure for which, on the other hand, no unequivocal evidence could be found. For the calculation, the peak intensities were corrected by atomic sensitivity factors (see Section 2) and average escape depths of  $m = 1.2$  nm for the photoemission electrons (700 to 900 eV kinetic energy) were assumed. Because the intensity  $I_O$  of the O 1s peak is given by

$$I_O = I_O^0 [I - \exp(-d/m)], \quad (1)$$

and the intensity  $I_N$  of the N 1s peak is given by

$$I_N = I_N^0 \exp(-d/m). \quad (2)$$

Assuming a layered particle surface structure model [14], the oxide layer thickness,  $d$ , can be derived from the ratio

$$\begin{aligned} \frac{I_O}{I_N} &= \frac{I_O^0 (I - \exp(-d/m))}{I_N^0 \exp(-d/m)} \\ &= \frac{I_O^0}{I_N^0 \exp(-d/m)} - \frac{I_O^0}{I_N^0} \end{aligned} \quad (3)$$

such that

$$d_{\text{XPS}} = m \ln \left( \frac{I_O I_N^0}{I_N I_O^0} + 1 \right) \quad (4)$$

where  $I_O$  and  $I_N$  are the measured O 1s and N 1s signal intensities and  $I_O^0$  and  $I_N^0$  are the theoretical XPS signal intensities that could be found with pure  $\text{SiO}_2$  or  $\text{Si}_3\text{N}_4$ , respectively. The ratio  $I_N^0/I_O^0$  is determined only by the relative atomic concentrations of nitrogen in  $\text{Si}_3\text{N}_4$  and oxygen in  $\text{SiO}_2$  [14], and a value of 1.03 was calculated.

Hence Equation 4 only holds under the simplifying assumption of a well-ordered layer structure of  $\text{SiO}_2$  on the  $\text{Si}_3\text{N}_4$  particle. Although earlier results have not shown a distinct oxide–nitride phase boundary but an oxynitride surface layer of various oxygen content [6], only a slightly larger thickness will be calculated when an oxynitride stoichiometry of the surface layer is assumed.

The equivalent surface layer thicknesses,  $d_{\text{XPS}}$ , as derived from Equation 4 are summarized in Table II. The thickness varies from 0.1 nm for powder B to 0.7 nm for powder G with an average value of 0.42 nm. The majority of the powders except powders B, D and F, reveal an oxide-rich layer thickness which corresponds only to one to two monolayers of silica with a  $\text{SiO}_4$ -tetrahedron size of  $\sim 0.265$  nm.

TABLE II Comparison of surface and bulk oxygen analyses

Powder	$S_v$ ( $\text{m}^2\text{g}^{-1}$ )	$C_O^t$ (wt %)	$d_s$ (nm)	$d_{\text{XPS}}$ (nm)	Fraction of surface oxygen (%)
A	7.3	1.4	1.6	0.4	25
B	12	0.9	0.6	0.1	17
C	8.8	1.3	1.2	0.7	58
D	10	1.4	1.2	0.2	17
E	15	1.5	0.9	0.4	44
F	21	1.3	0.5	0.14	28
G	15	2.4	1.4	0.7	51
H	10	2.5	2.1	0.5	24
I	12	1.4	1.0	0.6	60
K	12	0.9	0.6	0.5	83

The surface of powders B, D and F with  $d_{\text{XPS}} < 0.2$  nm might then be described as a layer of adsorbed oxygen rather than a consistent oxide or oxynitride film. The Si 2p signals also give no evidence for thicker oxidation layers and only powders with  $d_{\text{XPS}} > 0.4$  nm reveal a weak shoulder of the photoelectron peak at 102.8 eV due to enhanced Si–O bonding.

### 3.3. Surface and bulk oxygen

Table II also summarizes the results of specific surface area measurements by the BET-method and the total oxygen content of the silicon nitride powders as determined by chemical analysis. Using the specific surface area,  $S_v$ , an equivalent spherical particle diameter,  $D_s$ , can be calculated from the volume to surface ratio,  $v/s$ , of a sphere

$$D_s = 6 \frac{v}{s} = \frac{6}{\rho_{\text{SN}} S_v} = \frac{1.887 \times 10^{-6}}{S_v} \quad (5)$$

where  $\rho_{\text{SN}}$  is the density of the material, i.e.  $3.18 \times 10^6 \text{ g m}^{-3}$  in the case of  $\alpha\text{-Si}_3\text{N}_4$ .

If the total oxygen content of the powder,  $C_O^t$  was completely concentrated in a thin skin of  $\text{SiO}_2$  on the surface of spherical particles, a fictive surface layer thickness,  $d_s$ , could be calculated as follows: the volume of the  $\text{SiO}_2$  layer can be expressed as the difference between the total volume of the sphere with radius  $r_t$  and the volume of an unoxidized inner  $\text{Si}_3\text{N}_4$  core of radius  $r_i$

$$\frac{4}{3}\pi(r_t^3 - r_i^3) = \frac{4}{3}\pi r_t^3 \frac{\rho_{\text{SN}} K C_O^t}{\rho_{\text{SO}} 100} \quad (6)$$

$\rho_{\text{SN}}$ ,  $\rho_{\text{SO}}$ , and  $K$  are the densities of  $\alpha\text{-Si}_3\text{N}_4$ ,  $\text{SiO}_2$  (cristobalite), and a factor to convert wt % oxygen to wt %  $\text{SiO}_2$ , respectively.

Equation [6] is then transformed into

$$r_i = (1 - 0.02 C_O^t)^{1/3} r_t \quad (7)$$

and the thickness,  $d_s$ , of the surface oxide layer is given by

$$\begin{aligned} d_s &= r_t - r_i = [1 - (1 - 0.026 C_O^t)^{1/3}] r_t \\ &= [1 - (1 - 0.026 C_O^t)^{1/3}] \frac{D_s}{2} \end{aligned} \quad (8)$$

The fictive oxide layer thicknesses,  $d_s$ , were calculated for powders A to K using Equations 5 and 8 and the values are listed in Table II. Assumption of larger particle sizes,  $D_s$ , as obtained by electron microscopy or sedimentation analysis, leads to larger thicknesses  $d_s$  according to Equation 8. These two methods, however, do not take into account the particle shape and, therefore,  $D_s$  values derived from surface-area measurements seem more appropriate for a comparison with XPS data, because the latter technique also probes the total powder surface area.

Comparison of  $d_s$  with  $d_{\text{XPS}}$  values clearly shows a consistent discrepancy between the results from both methods: the  $d_{\text{XPS}}$  are always less than the oxidation layer thickness,  $d_s$ , calculated from the total oxygen content of the powders. Because for both models an identical  $\text{SiO}_2$  layer structure for the surface was assumed, this discrepancy can only be explained by a

distribution of oxygen on the particle surface and in the bulk. The ratio of the total oxygen content which is concentrated on the particle was then derived from the  $d_{\text{XPS}}/d_s$  ratio and is given in the last column of Table II. Obviously, the powders made by silicon diimide decomposition, I and K, have concentrated most of the total oxygen content on their surface, 0.8 to 0.9 wt %, whereas only a very small amount of less than 0.15 wt % (powder K) can be attributed to oxygen dissolved in the  $\alpha$ - $\text{Si}_3\text{N}_4$  crystal lattice. Powders A to F, which were made by nitridation of silicon, also show a very low amount of total oxygen but in general, except powder C, have more oxygen in the bulk, 0.6 to 1.1 wt %, than on the surface, 0.1 to 0.7 wt %. Finally, powders G and H, which were produced by carbothermal reduction of silica in a nitrogen atmosphere, are characterized by the highest amount of total oxygen of which 1.2 to 1.9 wt % are attributed to the bulk and 0.6 to 1.2 wt % to the surface. Some residual silica or silicon oxynitride may have resulted in the higher oxygen content of these powders.

From these results, an oxygen solubility in  $\alpha$ - $\text{Si}_3\text{N}_4$  of approximately  $0.8 \pm 0.2$  wt % at  $1400^\circ\text{C}$  is concluded. Earlier results corresponded to a solubility of 1.4 wt %, which was derived from an oxygen stabilized  $\alpha$ - $\text{Si}_{23}\text{N}_{30}\text{O}$  composition [7, 8]. Surface and bulk oxygen of the powders, however, has not been distinguished.

### 3.4. Oxygen control in the powders

The oxygen-rich surface layer is probably produced by oxidation of the ultrafine powders, when they are exposed to an oxygen or water-containing atmosphere. Low temperature and oxygen/water-free storage are required to avoid uncontrolled surface oxidation during manufacturing and powder processing.

Only the surface-bonded oxygen will be sensitive to chemical purification treatment of the powders. Leaching in anhydrous hydrofluoric acid or treatment in flowing gas mixture of argon/hydrogen at  $1300^\circ\text{C}$ , has successfully been used to reduce the oxygen content of silicon nitride powders [5]. Although the chemical treatment was effective in reducing the oxygen content, a residual oxygen content of approximately 1 wt % always remained. This minimum oxygen content corresponds well to the oxygen solubility as derived by the authors.

While the surface-bonded oxygen can be manipulated by surface active treatment, dissolved oxygen in the bulk can hardly be reduced after powder synthesis. For this reason further improvement of sinterable silicon nitride powders will also be focused on the reduction of dissolved oxygen in the bulk. Purified raw materials containing only a minimum amount of oxygen gettering impurities such as aluminium, magnesium, calcium, etc., are supposed to be of particular significance as well as low reaction temperatures during powder synthesis.

## 4. Conclusions

The oxygen distribution in silicon nitride powders was

investigated by bulk chemical analysis and surface sensitive XPS measurements. The majority of the powders, except the powders made by decomposition of silicon diimide, still contain an appreciable amount of oxygen in the bulk, from which an oxygen solubility of approximately 0.8 wt % was concluded.

A silica/silicon oxynitride composition is concluded for the particle surface layers, which were less than 1 nm thick. Chemical treatment can only reduce the surface-bonded oxygen content, while the dissolved oxygen remains in the bulk. The distribution of the oxygen contamination in a silicon nitride particle depends on the specific powder preparation method. Low-temperature synthesized silicon nitride powders from specifically purified materials are supposed to yield little oxygen in the bulk with a controlled oxygen distribution.

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